# ZETTLER DISPLAYS

XIAMEN ZETTLER ELECTRONICS CO., LTD.

# SPECIFICATIONS FOR LIQUID CRYSTAL DISPLAY

	CUSTOMER APP	ROVAL	
<b>* PART NO.:</b>	AQM1248A-RN-FBW-	P(ZETTLER DI	SPLAYS) VER2.2
APPROVAL		COMPANY CHOP	,
CUSTOMER COMMENTS			

DISPLAYTR	DISPLAYTRONIC ENGINEERING APPROVAL									
DESIGN BY	CHECKED BY	APPROVED BY								
WJQ	LH	GZH								

### **REVISION RECORD**

REVISION	REVISION DATE	PAGE	CONTENTS
VER1.0	2008-06-27		FIRST ISSUE
VER2.0	2008-07-29		CORRECT PIN DESCRIPTION
VER2.1	2014-10-17		ADD PATTERN LAYOUT
VER2.2	2014-10-20	P5	ADD PATTERN LAYOUT FOR SOLDERING
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### 1.0 GENERAL SPECS

1.	Overall Module Size (W*H*T)	34.8*20.3*10.0(MAX,include pin length)mm
2	Viewing Area (W*H)	32*11mm
2.	Dot Size(W*H)	0.20*0.17mm
3.	Dot Pitch(W*H)	0.22*0.19mm
4.	Driving Method	1/49Duty, 1/6Bias
5.	Controller IC	ST7565R
6.	LCD Type	FSTN,Positive ,Reflective
7.	Viewing Direction	6 O'Clock
8.	Backlight	NO
9.	Operating Temperature	Wide (-10°C ~ 50°C)
10	Rohs	Conforms

#### 2.0 ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min	Тур	Max	Unit
Operating temperature	Тор	-10	-	50	°C
Storage temperature	Tst	-20	-	60	°C
Input voltage	Vin	Vss		Vdd	V
Supply voltage for logic	Vdd- Vss	-	3.0	-	V
Supply voltage for LCD drive	Vdd- Vo	-	7.5	-	V

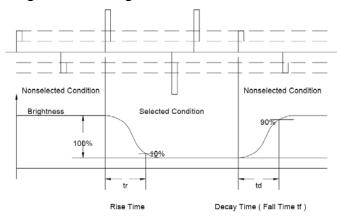
#### 3.0 ELECTRICAL CHARACTERISTICS

Item	Symbol	Condition	Min	Тур	Max	Unit
Power Supply Voltage	VDD	Ta=25°C	2.4	3.0	3.6	V
Power Supply Current	ldd	Vdd=3.0V	-	-	1.5	mA
Input voltage (high)	Vih	H level	0.8Vdd	-	Vdd	V
Input voltage (low)	Vil	L level	Vss	-	0.2Vdd	V
		-20°C	-	-	-	
Recommended LC Driving Voltage	Vdd -Vo	25°C	-	7.5	-	V
		70°C	-	-	-	

## 4.0 OPTICAL CHARACTERISTICS (Ta=25°C, Vdd= 3.0V±0.25V, FSTN LC fluid)

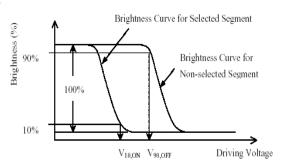
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ=90°		35	45	-	
Viouing angle	θ=270°	05 > 2.0	35	45	-	doa
Viewing angle	θ=0°	Cr ≥ 2.0	40	50	-	deg
	θ=180°		15	25	-	
Contrast Ratio	Cr	ф=0°	-	7	-	
Response time (rise)	Tr	θ=0°	-	100	150	ms
Response time (fall)	Tf	VLCD=7.5V	-	200	300	ms

# (1). Definition of Optical Response Time

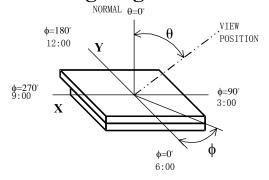


# (2). Definition of Driving Voltage (Vlcd)

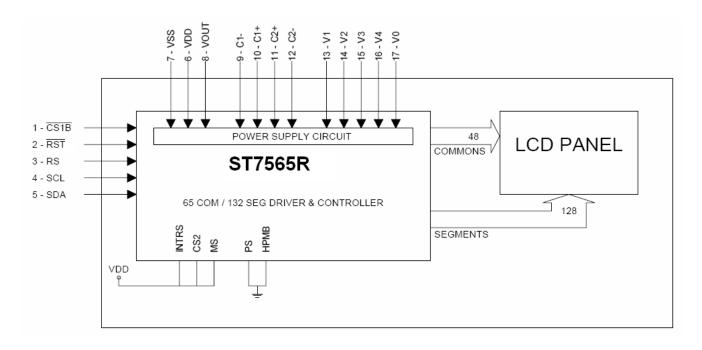
Vlcd=(V10,ON +V90,OFF)/2

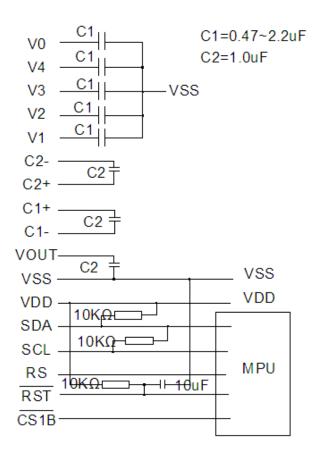


# (3). Definition of Viewing Angle $\theta$ and $\Phi$



#### 5.0 BLOCK DIAGRAM



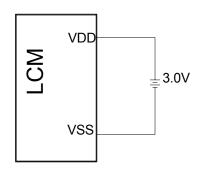


### PATTERN LAYOUT FOR SOLDERING

### **6.0 PIN ASSIGNMENT**

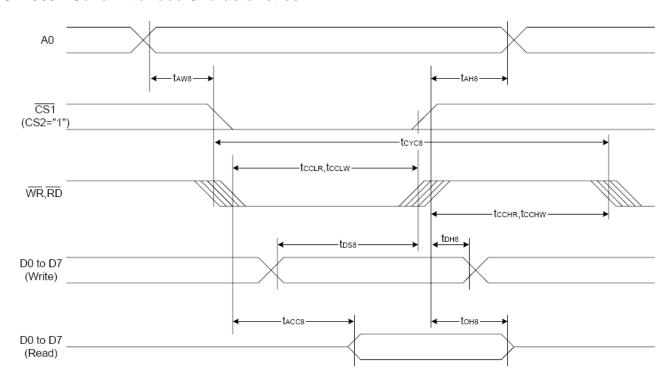
	.U FIN ASSIGNIVIENT										
PIN	SYMBOL	1/0	FUNCTION								
1	CS1B	I	Chip select input pin Data / instruction I/O is enabled only when CS1B is "L", When chip select is non-active, DB0 to DB7 may be high impedance.								
2	RST	I	Reset input pin When RST is "L", initialization is executed.								
3	RS	I	Register select input pin RS = "H": DB0 to DB7 are display data RS = "L": DB0 to DB7 are Instruction								
4	SCL		Serial interface selected (PS ="L");								
5	SDA	I/O	DB6: serial input clock (SCLK) DB7: serial input data (SID) When chip select is not active, DB6 and DB7 may be high impedance.								
6	VDD	Supply	Power supply								
7	VSS	Supply	Ground								
8	VOUT	I/O	Voltage converter input/output pin.								
9	C1-	0	Capacitor 1 negative connection pin for voltage converter.								
10	C1+	0	Capacitor 1 positive connection pin for voltage converter.								
11	C2+	0	Capacitor 2 positive connection pin for voltage converter.								
12	C2-	0	Capacitor 2 negative connection pin for voltage converter.								
13	V1		LCD driver supply voltages.								
14	V2		The voltage determined by LCD pixel is impedance-converted by an operational amplifier for								
15	V3	1/0	application.								
16	V4		Voltages should have the following relationship: V0>=V1>=V2>=V3>=V4>=VSS								
17	V0		V07-V17-V27-V37-V47-V33								

### 7.0 POWER SUPPLY



### **8.0 TIMING CHARACTERISTICS**

#### **ST7565P Serial Interface Characteristics:**



 $(VDD = 3.3V, Ta = -30 \text{ to } 85^{\circ}C)$ 

Item	Signal	Symbol	Condition	Rat	ing	Units
item	Signal	Symbol	Condition	Min.	Max.	Units
Address hold time		<b>t</b> AH8		0	_	
Address setup time	A0	t <sub>AW8</sub>		0	_	
System cycle time		tcyc8		240	_	
Enable L pulse width (WRITE)	WR	tcclw		80	_	
Enable H pulse width (WRITE)	VVIX	tcchw		80	_	
Enable L pulse width (READ)	RD	tcclr		140	_	Ns
Enable H pulse width (READ)	, KD	<b>t</b> cchr		80		
WRITE Data setup time		t <sub>DS8</sub>		40	_	
WRITE Address hold time	D0 to D7	<b>t</b> DH8		0	_	
READ access time	D0 10 D7	tacc8	CL = 100 pF	_	70	
READ Output disable time		<b>t</b> 0H8	CL = 100 pF	5	50	

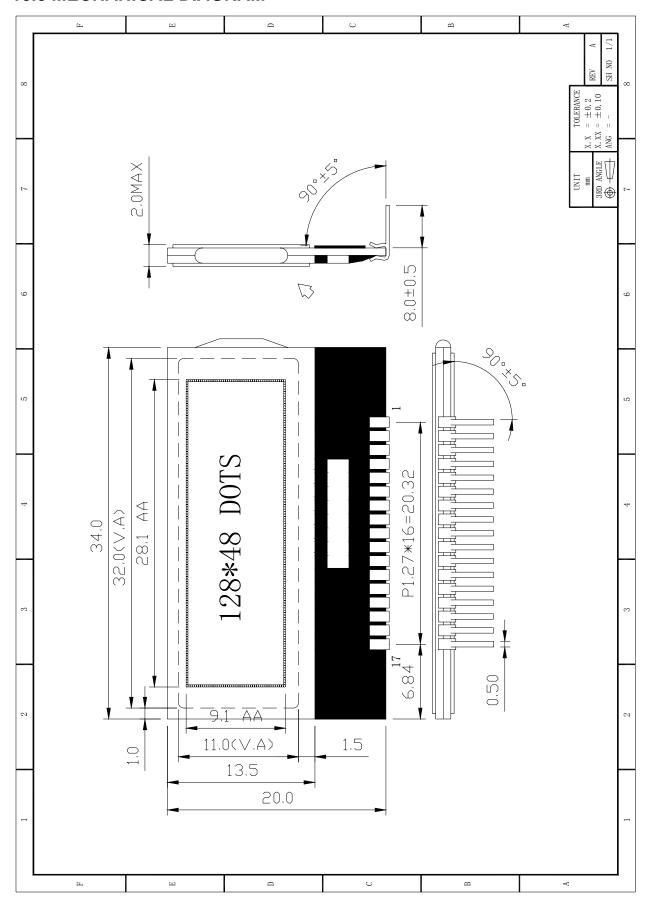
(VDD = 2.7V,Ta = -30 to 85°C)

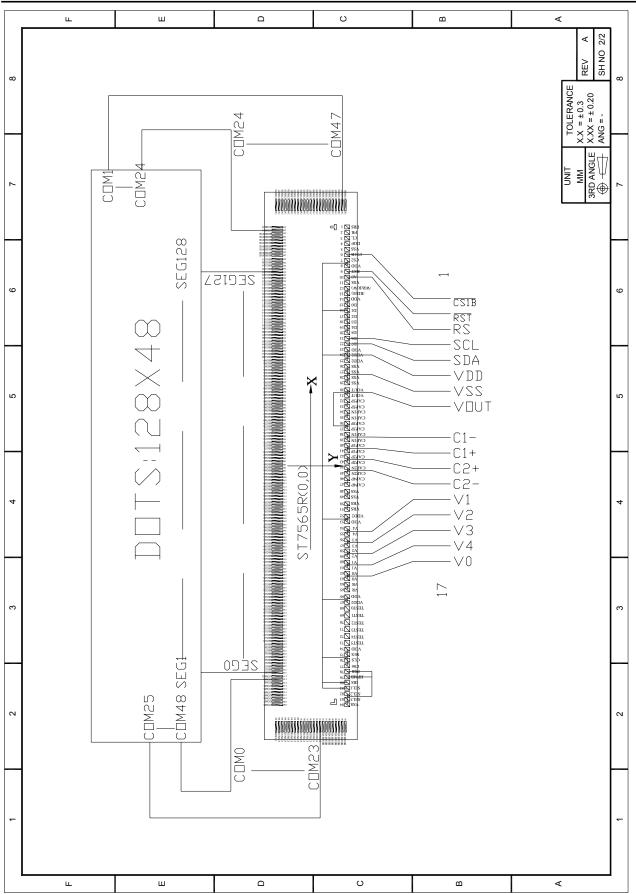
Item	Signal	Symbol	Condition	Rat	ing	Units
item	Signai	Symbol	Condition	Min.	Max.	Ullits
Address hold time		t <sub>AH8</sub>		0	_	
Address setup time	A0	taw8		0	_	
System cycle time		tcyc8		400	_	
Enable L pulse width (WRITE)	WR	tcclw		220	_	
Enable H pulse width (WRITE)	T VVR	<b>t</b> cchw		180	_	
Enable L pulse width (READ)	RD	tcclr		220	_	ns
Enable H pulse width (READ)		<b>t</b> cchr		180	_	
WRITE Data setup time		t <sub>DS8</sub>		40	_	
WRITE Address hold time	D0 to D7	<b>t</b> DH8		0	_	
READ access time	7 50 10 57	tacc8	CL = 100 pF	_	140	
READ Output disable time		<b>t</b> он8	CL = 100 pF	10	100	

# 9.0 COMMAND SETTING DESCRIPTION (Refer to the datasheet of ST7565R)

0	Command			Command Code								Function
Command	Α0	/RD	/WR	D7	D6	<b>D</b> 5	D4	D3	D2	D1	D0	Function
(1) Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0 1	LCD display ON/OFF 0: OFF, 1: ON
(2) Display start line set	0	1	0	0	1		Disp	ay st	art a	ddres	s	Sets the display RAM display start line address
(3) Page address set	0	1	0	1	0	1	1	Р	age	addre	ess	Sets the display RAM page address
(4) Column address set upper bit Column address set lower bit	0	1	0	0	0	0	1	co Le	lumn ast s	ignific addr ignific addr	ess cant	Sets the most significant 4 bits of the display RAM column address. Sets the least significant 4 bits of the display RAM column address.
(5) Status read	0	0	1		Sta	itus		0	0	0	0	Reads the status data
(6) Display data write	1	1	0					Wı	rite d	ata		Writes to the display RAM
(7) Display data read	1	0	1					Re	ad d	ata		Reads from the display RAM
(8) ADC select	0	1	0	1	0	1	0	0	0	0	0	Sets the display RAM address SEG output correspondence 0: normal, 1: reverse
(9) Display normal/ reverse	0	1	0	1	0	1	0	0	1	1	0	Sets the LCD display normal/ reverse 0: normal, 1: reverse
(10) Display all points ON/OFF	0	1	0	1	0	1	0	0	1	0	0 1	Display all points 0: normal display 1: all points ON
(11) LCD bias set	0	1	0	1	0	1	0	0	0	1	0 1	Sets the LCD drive voltage bias ratio 0: 1/9 bias, 1: 1/7 bias (ST7565R)
(12) Read-modify-write	0	1	0	1	1	1	0	0	0	0	0	Column address increment At write: +1 At read: 0
(13) End	0	1	0	1	1	1	0	1	1	1	0	Clear read/modify/write
(14) Reset	0	1	0	1	1	1	0	0	0	1	0	Internal reset
(15) Common output mode select	0	1	0	1	1	0	0	0	*	*	*	Select COM output scan direction 0: normal direction 1: reverse direction
(16) Power control set	0	1	0	0	0	1	0	1	0	perat mode		Select internal power supply operating mode
(17) V₀ voltage regulator internal resistor ratio set	0	1	0	0	0	1	0	0	Res	sistor	ratio	Select internal resistor ratio(Rb/Ra) mode
(18) Electronic volume mode set Electronic volume	0	1	0	1	0	0	0	0	0	0	1	Set the V <sub>0</sub> output voltage electronic volume register
register set				0	0	E	lectro	onic v	/olun	ne val	lue	electionic volume register
	_			1	0	1	0	1	1	0	0	0: Sleep mode, 1: Normal mode
(19) Sleep mode set	0	1	0	*	*	*	*	*	*	0	1	
(20) Booster ratio set	0	1	0	1	1	1	1	1	0	0	0	select booster ratio 00: 2x,3x,4x
(20) booster ratio set	U	1	0	0	0	0	0	0	0		p-up ilue	01: 5x 11: 6x
(21) NOP	0	1	0	1	1	1	0	0	0	1	1	Command for non-operation
(22) Test	0	1	0	1	1	1	1	*	*	*	*	Command for IC test. Do not use this command

### **10.0 MECHANICAL DIAGRAM**





### 11.0 RELIABILITY TEST

NO	Te	st Item	Description	Test Condition	Remark
1		High temperature storage	Applying the high storage temperature Under normal humidity for a long time Check normal performance	80 <b>°</b> C 96hrs	
2		Low temperature storage	Applying the low storage temperature Under normal humidity for a long time Check normal performance	-30 <b>°</b> C 96hrs	
3		High temperature Operation	Apply the electric stress(Voltage and current) Under high temperature for a long time	70 °C 96hrs	Note1
4	Environmental Test	Low temperature Operation	Apply the electric stress Under low temperature for a long time	-20 <b>°</b> C 96hrs	Note1 Note2
5	Test	High temperature/High Humidity Storage	Apply high temperature and high humidity storage for a long time	90% RH 40 <b>º</b> C 96hrs	Note2
6	6	Temperature Cycle	Apply the low and high temperature cycle -30°C <> 25°C <> 80°C <> 25°C 30min 10min 30min 10min  1 cycle Check normal performance	-30°C/80°C 10 cycle	
7	Mechanical Test	Vibration test(Package state)	Applying vibration to product check normal performance	Freq:10~55~10Hz Amplitude:0.75mm 1cycle time:1min X.Y.Z every direction for 15 cycles	
8		Shock test(package state)	Applying shock to product check normal performance	Drop them through 70cm height to strike horizontal plane	
9	Other			_	

#### Remark

Note1:Normal operations condition (25°C±5°C).

Note2:Pay attention to keep dewdrops from the module during this test. Ds subjected to the test must not have dew condensation.

## **12.0 APPEARANCE CRITERIA**

Item	Description	Picture	Specification			MA	MI	Inspection Method	
Dot defects (black/whi te dot)	Scratches black dot white dot on the polarizer dirty spot and bubble between the polarizer and glass in the display area.	$\Phi = \frac{a+b}{2}$ J:the distance between dot and dot.	≤0.1		Ignored				Visual/ contrast by Inspection standard film
			0.1< ∮ ≤0.20		2	J>5			
			0.20< ∮ ≤0.25		1	J>10	•		
			0.25< ∮ ≤0.30		0				
			0φ>0.3		0				
black/white line defect	Fibres in active area, scratches and black line on the glass or polarizer.	L	W≤0.01		Ignored		•		Visual/
			W≤0.02 L≤5		2	J>5			contrast by
(straight line or			W≤0.03 L≤4		1	J>10			Inspection standard
curve etc. Line type			W≤0.04 L≤3		0	J>10			film
defects)		J:the distance between dot and dot.	W≤0.05 L≤2		0				
Chip on corner	sidestep on the lower glass	Y:width of chip X:length of chip L:width of sidestep J:distance between electrode and the farthermost edge.	Y≤1/2L, X≤1		Ignored		-	•	Visual/ contrast by Inspection standard film
			Y≤1/2L, X≤2		2				
			Y≤1/2L, X≤3		1				
			Y≤1/2L, X≤1/3	3J	0	J≤3			
			Y≤1/2L, X≤2/3	J	0	J≤3			
Crack	X:length of cra L:width of side	Y:width of crack X:length of crack L:width of sidestep T:deepth of crack Z:thickness of single	Y≤1/5L X≤5 ≤1/2T	X≤5 Z Ignored				Visual/ contrast	
			Y≤1/4L X≤5 ≤1/2T	Z	2				by Inspection standard
			Y≤1/3L X≤5 Z≤ 1/2T		1			•	film
			Y≤1/3L X≤10 ≤1/2T	Z	Z 0				
			Y≤1/3L X≤15 ≤1/2T	Z	0				
Crack			Cracks in any area	rejed	cted		•		Visual
Polarizer			≤0.8	Acc	epted			•	Visual/

		be applicable for	0.8 <l≤1.0< th=""><th>Rejected</th><th></th><th>contrast</th></l≤1.0<>	Rejected		contrast
	up/bottom polarizer	1.0 <l≤1.5< td=""><td>Rejected</td><td></td><td>Inspection standard</td></l≤1.5<>	Rejected		Inspection standard	
			1.5 <l≤2.0< td=""><td>Rejected</td><td></td><td>film</td></l≤2.0<>	Rejected		film
			Any seeable polarizer slanting or excursion in active area will be rejected.			
			The polarizer edo be line. Any inde silkscreen line wi			
				missing or extra, for polarizer and dirty on polarizer will be		
			seeable black sill arond can be acc	kscreen line from the cepted.		
			Refer to the draw	ving size requirement.		
End seal			UV glue of seal on the glass surface	Rejected	-	Visual/ contrast by
		L:The distance from the block to edge of glass.	The UV glue of seal overflow into the active area.	Rejected		Inspection standard film
			Direction of end seal is different from the drawing.	Rejected		
			Glue capacity of end seal < (1/3)*L	Rejected		
			the height and length of end seal is out of the drawing requirements.	Rejected		
Silkscreen line		silkscreen line overflow into the active area.	Rejected		Visual/ contrast by Inspection	
		silkscreen line deviated in active area.	Rejected		standard	
			bubble of silkscreen line ≥ 1/3 witdth of silkscreen line	Rejected		

PIN		Glue on PIN: there is glue on the PIN without pin clip will be rejected. PIN glue solidification: PIN glue doesn't solidify completely. The sunken or glue stain by touching will be rejected.  PIN deflection: if deflection angle > ± 5°, rejected; contrarily, please refer to the drawing requirement. Without continuous glue on pins will be rejected.  PIN glue stains on polarizer or inleakage polarizer and glass, rejected.  PIN glue exceeds the up polarizer, rejected.  Missing or extra, broken pin, rejected.  PIN loosen: no permission for pin loose or drop.  Clip PIN:pin center exceeds 1/3 ITO width, rejected.  No pin glue, rejected.  Vy glue range: UV glue must be exceeded over 1~1.5 pin distance from both side. if not, rejected.  PIN length and direction must be same with the drawing requirements.				Visual/ contrast by Inspection standard film
Protective film		LCD protective film can not stick on the polarizer and the product protective film raised ≤1/3 length or width of polarizer from same direction of axis and its total length should be ≤15mm. This defect can be accepted.			•	Visual
Rainbow		rainbow is not in active area.	Accepted			Visual/co ntrast by
		Rainbow in active area.	Rejected		•	golden sample
		with obvious discoloration and uneven color.	Rejected			
backgroud color		There are obvious different background color from the same product lot.	Rejected		•	Visual/co ntrast by golden sample

#### NOTE:

Inspection condition:

Viewing distance for cosmetic inspection is 30cm with bare eyes, and under an environment of 800 lux(20W\*2---40W) light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

#### 13.0 PRECAUTION FOR USING LCM

- 1. When design the product with this LCD Module, make sure the viewing angle matches to its purpose of usage.
- 2. As LCD panel is made of glass substrate, Dropping the LCD module or banging it against hard objects may cause cracking or fragmentation. Especially at corners and edges.
- 3. Although the polarizer of this LCD Module has the anti-glare coating, always be careful not to scratch its surface. Use of a plastic cover is recommended to protect the surface of polarizer.
- 4. If the LCD module is stored at below specified temperature, the LC material may freeze and be deteriorated. If it is stored at above specified temperature, the molecular orientation of the LC material may change to Liquid state and it may not revert to its original state. Excessive temperature and humidity could cause polarizer peel off or bubble. Therefore, the LCD module should always be stored within specified temperature range.
- 5. Saliva or water droplets must be wiped off immediately as those may leave stains or cause color changes if remained for a long time. Water vapor will cause corrosion of ITO electrodes.
- 6. If the surface of LCD panel needs to be cleaned, wipe it swiftly with cotton or other soft cloth. If it is not still clean enough, blow a breath on the surface and wipe again.
- 7. The module should be driven according to the specified ratings to avoid malfunction and permanent damage. Applying DC voltage cause a rapid deterioration of LC material. Make sure to apply alternating waveform by continuous application of the M signal. Especially the power ON/OFF sequence should be kept to avoid latch-up of driver LSIs and DC charge up to LCD panel.
- 8. Mechanical Considerations
  - a) LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.
  - b) Do not tamper in any way with the tabs on the metal frame.
  - c) Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattern.
  - d) Do not touch the elastomer connector; especially insert a backlight panel (for example, EL).
  - e) When mounting a LCM makes sure that the PCB is not under any stress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
  - f) Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.
- 9. Static Electricity
  - a) Operator

Ware the electrostatics shielded clothes because human body may be statically charged if not ware shielded clothes. Never touch any of the conductive parts such as the LSI pads; the copper leads on the PCB and the interface terminals with any parts of the human body.

b) Equipment

There is a possibility that the static electricity is charged to the equipment, which has a function of peeling or friction action (ex: conveyer, soldering iron, working table). Earth the equipment through proper resistance (electrostatic earth: 1x10<sup>8</sup> ohm).

Only properly grounded soldering irons should be used.

If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

c) Floor

Floor is the important part to drain static electricity, which is generated by operators or equipment.

There is a possibility that charged static electricity is not properly drained in case of insulating floor. Set the electrostatic earth (electrostatic earth: 1x10<sup>8</sup> ohm).

d) Humidity

Proper humidity helps in reducing the chance of generating electrostatic charges. Humidity should be kept over 50%RH.

e) Transportation/storage

The storage materials also need to be anti-static treated because there is a possibility that the human body or storage materials such as containers may be statically charged by friction or peeling.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

f) Soldering

Solder only to the I/O terminals. Use only soldering irons with proper grounding and no leakage.

Soldering temperature : 280 $^{\circ}$  C  $\pm$  10 $^{\circ}$  C

Soldering time: 3 to 4 sec.

Use eutectic solder with resin flux fill.

If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed afterwards.

g) Others

The laminator (protective film) is attached on the surface of LCD panel to prevent it from scratches or stains. It should be peeled off slowly using static eliminator.

Static eliminator should also be installed to the workbench to prevent LCD module from static charge.

#### 10. Operation

- a) Driving voltage should be kept within specified range; excess voltage shortens display life.
- b) Response time increases with decrease in temperature.
- c) Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- d) Mechanical disturbance during operation (such as pressing on the viewing area) may cause the segments to appear "fractured".
- 11. If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. The toxicity is extremely low but caution should be exercised at all the time.
- 12. Disassembling the LCD module can cause permanent damage and it should be strictly avoided.
- 13. LCD retains the display pattern when it is applied for long time (Image retention). To prevent image retention, do not apply the fixed pattern for a long time. Image retention is not a deterioration of LCD. It will be removed after display pattern is changed.
- 14. Do not use any materials, which emit gas from epoxy resin (hardener for amine) and silicone adhesive agent (dealcohol or deoxym) to prevent discoloration of polarizer due to gas.
- 15. Avoid the exposure of the module to the direct sunlight or strong ultraviolet light for a long time.